Claims

[c1] A method of manufacturing a printed circuit board comprising the steps of:
preparing an insulating substrate having a front surface and a back surface, and a layer of metal foil formed on each of said front surface and said back surface;
selectively forming a plating layer for forming a land on at least one of said metal foils;
adjusting a thickness of said plating layer; and
forming said metal foils into lines.

[c2] The manufacturing method according to Claim 1, wherein said adjusting step includes a step of polishing a surface of said plating layer.

[c3] The manufacturing method according to Claim 1, further comprising the steps of:
forming a dielectric layer on said insulating substrate, said land and said lines;
forming an opening in said dielectric layer on said land; and
performing plating on said opening.

[c4] The manufacturing method according to Claim 2, further

comprising the steps of:
forming a dielectric layer on said insulating substrate, said land and said lines;
forming an opening in said dielectric layer on said land; and
performing plating on said opening.

[c5] A method of manufacturing a printed circuit board comprising the steps of:
preparing an insulating substrate having a front surface and a back surface, and a layer of metal foil formed on each of said front surface and said back surface;
forming an opening in at least one of said metal foils and said insulating substrate;
forming a first resist pattern on said metal foil;
forming a plating layer on an inner surface of said opening and the exposed metal foil;
adjusting a thickness of said plating layer on said metal foil; and
forming said metal foil into lines.

[c6] The manufacturing method according to Claim 5, wherein said step of forming into lines comprising the steps of:
removing said first resist pattern;
forming a second resist pattern on said metal foil and said plating layer;

selectively forming an exposed portion of said metal foil using said second resist pattern;
etching said metal foil at said exposed portion; and
removing said second resist pattern.

[c7] The manufacturing method according to Claim 6, further comprising the steps of:
forming a dielectric layer on said insulating substrate and on said plating layer and said lines on said metal foil;
forming an opening in said plating layer; and
performing plating on said opening.

[c8] The manufacturing method according to Claim 5, wherein said adjusting step includes a step of polishing a surface of said plating layer.

[c9] The manufacturing method according to Claim 6, wherein said adjusting step includes a step of polishing a surface of said plating layer.

[c10] The manufacturing method according to Claim 7, wherein said adjusting step includes a step of polishing a surface of said plating layer.

[c11] The manufacturing method according to Claim 8, wherein said step of polishing includes polishing using a belt sander or a buff.

[c12] The manufacturing method according to Claim 9, wherein said step of polishing includes polishing using a belt sander or a buff.

[c13] The manufacturing method according to Claim 10, wherein said step of polishing includes polishing using a belt sander or a buff.

[c14] A printed circuit board comprising:
an insulating substrate having a front surface and a back surface;
a line of metal foil selectively formed on at least one of said front surface and said back surface;
a land selectively formed on at least one of said front surface and said back surface, said land being formed of a stack of said metal foil and a plating layer;
a dielectric layer formed on an exposed portion and said line; and
a via hole formed on said land.